

Filename: PMP7188 REV_B_bom.xls

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PMP7188 REV_B BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C1	2.2nF	Capacitor, Ceramic, 630V, X7R, 10%	1206	C3216X7R2J222K	TDK
1	C2	0.22 uF	Capacitor, Film, 250VAC, 20%	0.689 x 0.217	ECQU2A224MV	Panasonic
1	C3	33 uF	Capacitor, Alum Electrolytic 16mm x 20mm, 450V, ±20%	16.00 mm Dia	EKXJ451ESS330ML20S	Nippon Chemi-Con
1	C6	1000uF	Capacitor, Aluminum, 10mm x 16mm, 16V, 105C, 20%	10mm	EKZM160ESS102MJ16S	Nippon Chemi-con
1	C8	0.22uF	Capacitor, Ceramic, 25V, X5R, 10%	0603	C1608X7R1H473K	TDK
1	C9	5.6nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	TDK
1	C10	1uF	Capacitor, Ceramic, 16V, X7R, 20%	0603	C1608X7R1C105M	TDK
1	C11	22nF	Capacitor, Ceramic, Low Inductance, 50V, X7R, 10%	0603	Std	Std
1	C12	220pF	Capacitor, Ceramic, Low Inductance, 50V, X7R, 10%	0603	Std	Std
1	C13	470pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C14	2.2uF	Capacitor, Ceramic, 16V, X5R, 10%	0603	Std	Std
1	C15	1500pF	CAP, CERM DISC Y1, 250Vac, 20%	.500 X .310	ECKDNA152ME	Panasonic
3	C4-5 C7	10uF	Capacitor, Ceramic, 25V, X5R, 20%	1210	C3225X5R1E106M	TDK
1	C100	4.7uF	Capacitor, Ceramic, 25V, X5R, 20%	1206	Std	Std
1	D1	KBP06G	Diode, Bridge Rectifier, 1.5A, 600V	0.580 x 0.145 inch	KBP06G	Diodes
1	D2	MBRB10100	Diode, Schottky, 10A, 100V	TO-263AB	MBRB10100	Vishay
1	D3	MURA160T3	Diode, Rectifier, 1A, 600V	SMA	MURA160T3	ON Semiconductor
1	D4	CRH01	Diode, Switching, 200-V, 1-A	SOD-123	CRH01	Toshiba
1	D5	BAS40-04-V	Diode, Dual Series, 40V, 200mA	SOT23	BAS40-04-V	Diodes
1	F1	2A	Fuse, TR5 Time Lag, 2A, 250V	0.335	3831200000	Littlefuse
1	L1	20mH	Inductor, Common Mode, 0.5 A, 540 milliohm	12.5x18 mm	744822120	Wuerth
1	L2	1.2uH	Inductor, SMT, 5.3A, 17milliohm	0.350 x 0.300 inch	DO1813HC-122ML	Coilcraft
1	Q1	SPD03N60C3	MOSFET, N-ch, 650-V, 4-A, 1.4-Ohms	DPAK	SPD03N60C3	Infineon
1	R4	2.2	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R5	47	Resistor, Chip 1/4 watt, ± 5%	1206	Std	Std
1	R6	275V	Varistor, 275V	0.472 x 0.213 inch	SIOV-S10K275E2	Epcos
1	R8	2.2	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R9	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R10	1K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R13	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R14	38.3K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R15	25.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R16	18.2k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R17	475	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R18	0.47	Resistor, Chip, 1/10W, 1%	0805	Std	Std
2	R1 R7	1M	Resistor, Chip 1/4 watt, ± 5%	1206	Std	Std
3	R11-12 R19	10K	Resistor, Chip, 1/16W, 1%	0603	Std	Std

2	R2-3	22k	Resistor, Chip, 1-W, 5%	2512	Std	Std
1	RT1	10 Ohm	Thermistor, 8.5mm diam.	0.236 X 0.512 inch	B57153S0100M000	Epcos
1	T1	0.94 mH	Transformer, Flyback Converter ±10%	21x25 mm	SP-E20/6	Kaschke
1	TP4	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
5	TP1-3 TP5-6	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	U1	LM5021-2	IC, AC-DC Current Mode PWM Controller	MSOP	LM5021MMX-2	TI
1	U2	TCMT1107	IC, Photocoupler	MF4	TCMT1107	Vishay
1	U3	TL431AIDBZ	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZ	TI

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk (***) cannot be substituted.
All other components can be substituted with equivalent MFG's components.

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